



Qualification Test Report Of EP2.5 Taping Version Header

1. INTRODUCTION

1.1 Purpose

Testing was performed on the EP 2.5 taping version header for qualification.

1.2 Scope

This specification covers mechanical performance of the EP2.5 taping version header per Product Specification 108-2418. Testing was performed at TE Connectivity Shanghai Electrical Test Laboratory between 25Jul, 2016 and 28Jul, 2016. The associated test number is TP-16-02169 & TP-16-02171.

1.3 Conclusion

Refer to Section 2- Testing result.

1.4 Test Specimens

The test specimens were identified with the following part numbers and types:

Table with 3 columns: Description, PN, Part Revision. Rows include EP2.5 taping version header, 2pos.yellow color and EP2.5 taping version header, 8pos.yellow color.

1.5 Test Sequence

Table with 3 columns: Test Item, Test Group 1, Test Group 2. Rows include Adherence force of taping, Post retention force before soldering, Resistance to Soldering Heat, and Post retention force after soldering.

Note: a). Test group defined per requirement.

b). Numbers indicate sequence in which tests are performed

1.6 Environmental Conditions

Unless otherwise specified, all the test shall be performed in any combination of the following test conditions.

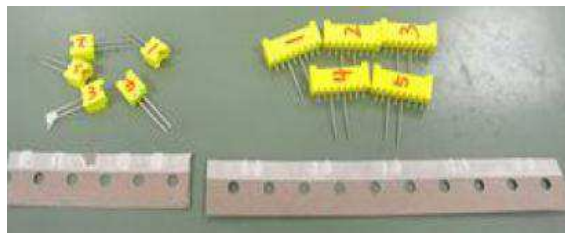
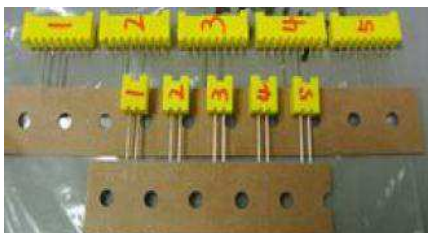
Temperature: 15°C to 35°C
 Relative Humidity: 25% to 75%

2. TESTING RESULT

2.1 Adherence force of taping

All samples can meet TE spec (20N min.)

Sample	2Pin	8Pin
1	24.37	27.54
2	23.51	31.40
3	22.65	29.14
4	21.81	23.63
5	25.81	25.48
Max.	25.81	31.40
Min.	21.81	23.63
Ave.	23.63	27.44



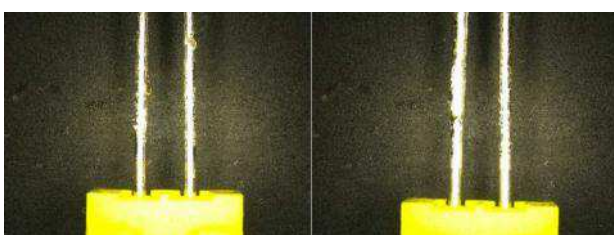
2.2 Post Retention Force (before soldering)

The post retention force before soldering can meet TE spec (20N min.)

Post retention force		
Pin	2pos.	8pos.
1	38.93	38.73
2	42.75	39.94
3	43.62	41.41
4	40.46	38.45
5	46.28	37.42
6	42.70	39.56
7	43.19	42.14
8	43.27	36.34
9	46.27	41.51
10	41.39	41.22
11		44.18
12		40.22
13		42.22
14		39.26
15		40.42
16		39.53
17		37.25
18		37.92
19		41.73
20		39.02
Max.	46.28	44.18
Min.	38.93	36.34
Average	42.89	39.92

2.3 Resistance to Soldering Heat

All samples has no evident physical damage after heat soldering.



2.4 Post Retention Force (after soldering)

The post retention force after soldering can meet TE spec (20N min.)

Post retention force		
Pin	2pos.	8pos.
1	24.97	26.76
2	24.33	30.35
3	24.20	26.78
4	23.74	25.47
5	28.64	25.12
6	29.47	24.36
7	29.63	31.21
8	32.01	30.64
9	22.22	28.68
10	26.97	33.10
11		31.34
12		31.11
13		26.51
14		32.37
15		33.18
16		33.87
17		29.35
18		30.26
19		25.75
20		28.25
Max.	32.01	33.87
Min.	22.22	24.36
Average	26.62	29.22